



SPECIAL INSTRUCTIONS :

PRODUCT INFORMATION

Customer :	
Device :	Device ID :
Die Size :	Wafer Material :
Package Type :	No. of Wires :

MATERIAL INFORMATION

Leadframe :	Pad Size :
Epoxy :	Wire size :
Molding Compound :	Lead Finish :

MARKING INSTRUCTION

TOP :	BOTTOM :

BONDING DIAGRAM NO.

REF. BONDING DIAGRAM NO.

SCALE
not to scale

DRAWN BY: _____ REVIEWED BY : _____

REVISION NO. APPROVALS

REV. #	DESCRIPTION	PCN #	DEPT	APPROVALS	DATE
			CUST		
			QSM		
			QC		
			MFG		